24-RGB MATRIX LED DRIVER



Preliminary Information September 2018

GENERAL DESCRIPTION

The IS31FL3746A is a general purpose 18×n (n=1~4) LED Matrix programmed via 1MHz I2C compatible interface. Each LED can be dimmed individually with 8-bit PWM data and 8-bit DC scaling (Color Calibration) data which allowing 256 steps of linear PWM dimming and 256 steps of DC current adjustable level.

Additionally each LED open and short state can be detected, IS31FL3746A store the open or short information in Open-Short Registers. The Open-Short Registers allowing MCU to read out via I2C compatible interface. Inform MCU whether there are LEDs open or short and the locations of open or short LEDs.

The IS31FL3746A operates from 2.7V to 5.5V and features a very low shutdown and operational current.

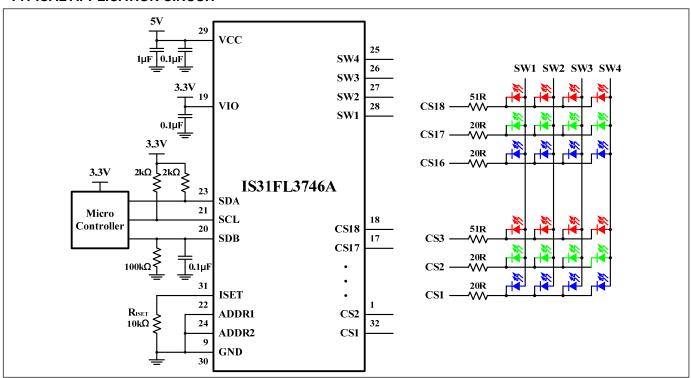
IS31FL3746A is available in QFN-32 (4mm×4mm) package. It operates from 2.7V to 5.5V over the temperature range of -40°C to +125°C.

FEATURES

- Supply voltage range: 2.7V to 5.5V
- 18 current sinks
- Support 18×n (n=1~4) LED matrix configurations
- Individual 256 PWM control steps
- Individual 256 DC current steps
- Global 256 current steps
- SDB rising edge reset I2C module
- 29kHz PWM frequency
- 1MHz I2C-compatible interface
- State lookup registers
- Individual open and short error detect function
- De-Ghost
- QFN-32 (4mm×4mm) package

APPLICATIONS

- Hand-held devices for LED display
- Gaming device (Mouse, Mouse MAT etc.)
- IOT device (AI speaker etc.)



TYPICAL APPLICATION CIRCUIT

Note 1: For the mobile applications the IC should be placed far away from the mobile antenna in order to prevent the EMI. **Note 2:** The 20R and 50R between LED and IC are only for thermal reduction.

Figure 1 Typical Application Circuit: 18×4, 24 RGBs



TYPICAL APPLICATION CIRCUIT (CONTINUED)

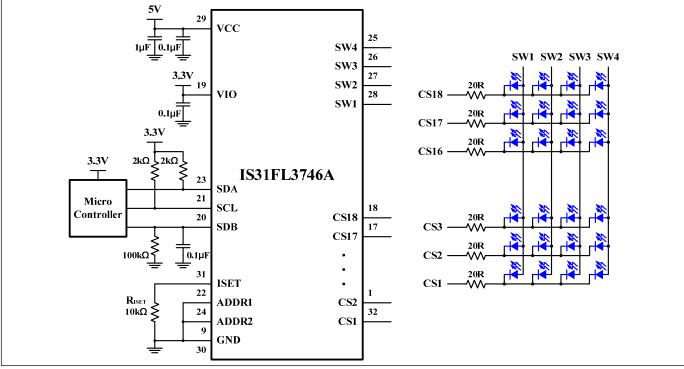
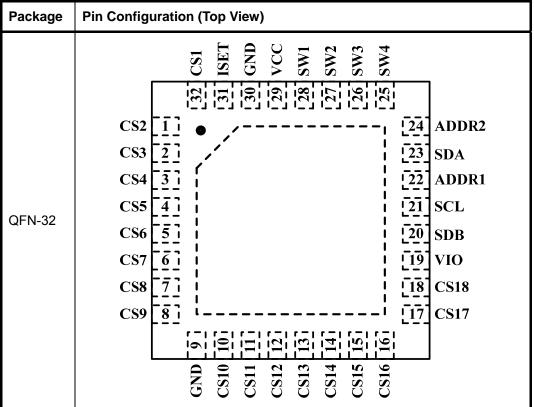


Figure 2 Typical Application Circuit: 72 Mono Color LEDs

Note 3: The 20R between LED and IC are only for thermal reduction, for red LED, V_{CC} can be 3.3V, don't need these resistors.



PIN CONFIGURATION



PIN DESCRIPTION

No.	Pin	Description	
28~25	SW1~SW4	Power SW.	
18~10,8~1,32	CS18~CS1	Current sink pin for LED matrix.	
9,30	GND	Ground.	
19	VIO	Input logic reference voltage, can't be floated.	
20	SDB	Shutdown pin.	
21	SCL	I2C compatible serial clock.	
22	ADDR1	I2C address select.	
23	SDA	I2C compatible serial data.	
24	ADDR2	I2C address select.	
29	VCC	Power for current source SW and analog.	
31	ISET	Set the maximum IOUT current.	
	Thermal Pad	Connect to GND.	



ORDERING INFORMATION Industrial Range: -40°C to +125°C

Order Part No.	Package	QTY/Reel
IS31FL3746A-QFLS4-TR	QFN-32, Lead-free	2500

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b.) the user assume all such risks; and

c.) potential liability of Integrated Silicon Solution, Inc is adequately protected under the circumstances



ABSOLUTE MAXIMUM RATINGS

Supply voltage, V _{CC}	-0.3V ~+6.0V
Voltage at any input pin	$-0.3V \sim V_{CC} + 0.3V$
Maximum junction temperature, T _{JMAX}	+150°C
Storage temperature range, T _{STG}	-65°C ~+150°C
Operating temperature range, $T_A = T_J$	-40°C ~ +125°C
Package thermal resistance, junction to ambient (4 layer standard test PCB based on JESD 51-2A), θ_{JA}	52°C/W
ESD (HBM)	±8kV
ESD (CDM)	±750V

Note 4: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other condition beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

The following specifications apply for V_{CC} = 5V, T_A = 25°C, unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
V _{cc}	Supply voltage		2.7		5.5	V
I _{CC}	Quiescent power supply current	$V_{SDB}=V_{CC,}$ all LEDs off		2		mA
		V _{SDB} =0V		1		
I _{SD}	Shutdown current	V _{SDB} = V _{CC} , Configuration Register written "0000 0000		1		μA
I _{OUT}	Maximum constant current of CSx	R _{ISET} =10kΩ, GCC=0xFF SL=0xFF		34		mA
I _{LED}	Average current on each LED $I_{LED} = I_{OUT(PEAK)}/Duty(4.14)$	R _{ISET} =10kΩ, GCC=0xFF SL=0xFF		8.2		mA
N/	Current switch headroom voltage SWx	I _{SWITCH} =612mA R _{ISET} =10kΩ, GCC=0xFF, SL=0xFF		400		
V_{HR}	Current sink headroom voltage CSx	I _{SINK} =34mA, R _{ISET} =10kΩ, GCC=0xFF, SL=0xFF		300		mV
t _{SCAN}	Period of scanning			33		μs
t _{NOL1} Non-overlap blanking time during scan, the SWx and CSy are all off during this time				0.83		μs
t _{NOL2}	Delay total time for CS1 to CS 18, during this time, the SWx is on but CSx is not all turned on	(Note 5)		0.3		μs
Logic El	ectrical Characteristics (SDA, SCI	L, ADDRx, SDB)				
V _{IL}	Logic "0" input voltage	V _{IO} =1.8V; V _{IO} =3.3V	GND		$0.2V_{IO}$	V
V _{IH}	Logic "1" input voltage	V _{IO} =1.8V; V _{IO} =3.3V	0.75V _{IO}		V _{IO}	V
V_{HYS}	Input Schmitt trigger hysteresis	V _{IO} =3.3V		0.2		V
I _{IL}	Logic "0" input current	V _{INPUT} = 0V (Note 5)		5		nA
I _{IH}	Logic "1" input current	V _{INPUT} = V _{IO} (Note 5)		5		nA



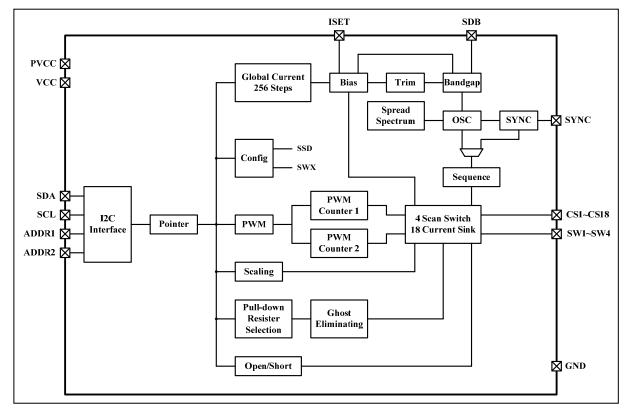
DIGITAL INPUT IIC SWITCHING CHARACTERISTICS (NOTE 5)

Cumbal	Parameter		Fast Mode			Fast Mode Plus		
Symbol			Тур.	Max.	Min.	Тур.	Max.	Units
f _{SCL}	Serial-clock frequency	-		400	-		1000	kHz
t _{BUF}	Bus free time between a STOP and a START condition	1.3		-	0.5		-	μs
t _{hd, sta}	Hold time (repeated) START condition	0.6		-	0.26		-	μs
t _{su, sta}	Repeated START condition setup time	0.6		-	0.26		-	μs
t _{su, sто}	STOP condition setup time	0.6		-	0.26		-	μs
t _{HD, DAT}	Data hold time	-		-	-		-	μs
t _{su, dat}	Data setup time	100		-	50		-	ns
t _{LOW}	SCL clock low period	1.3		-	0.5		-	μs
t _{HIGH}	SCL clock high period	0.7		-	0.26		-	μs
t _R	Rise time of both SDA and SCL signals, receiving	-		300	-		120	ns
t _F	Fall time of both SDA and SCL signals, receiving	-		300	-		120	ns

Note 5: Guaranteed by design.



FUNCTIONAL BLOCK DIAGRAM



DETAILED DESCRIPTION

I2C INTERFACE

IS31FL3746A uses a serial bus, which conforms to the I2C protocol, to control the chip's functions with two wires: SCL and SDA. The IS31FL3746A has a 7-bit slave address (A7:A1), followed by the R/W bit, A0. Set A0 to "0" for a write command and set A0 to "1" for a read command. The value of bits A1 and A2 are decided by the connection of the ADDRx pin.

Table 1 Slave Ad	dress:
------------------	--------

ADDR2	ADDR1	A7:A5	A4:A3	A2:A1	A0
GND	GND		00	00	
GND	SCL		00	01	
GND	SDA		00	10	
GND	VCC		00	11	
SCL	GND		01	00	
SCL	SCL		01	01	
SCL	SDA		01	10	
SCL	VCC	110	01	11	0/4
SDA	GND	110	10	00	0/1
SDA	SCL		10	01	
SDA	SDA		10	10	
SDA	VCC		10	11	
VCC	GND		11	00	
VCC	SCL		11	01	
VCC	SDA		11	10	
VCC	VCC		11	11	

ADDR1/2 connected to GND, (A2:A1)/(A4:A3)=00; ADDR1/2 connected to VCC, (A2:A1)/(A4:A3)=11; ADDR1/2 connected to SCL, (A2:A1)/(A4:A3)=01; ADDR1/2 connected to SDA, (A2:A1)/(A4:A3)=10;

The SCL line is uni-directional. The SDA line is bidirectional (open-collector) with a pull-up resistor (typically 400kHz IIC with 4.7k Ω , 1MHz IIC with 1k Ω). The maximum clock frequency specified by the I2C standard is 1MHz. In this discussion, the master is the microcontroller and the slave is the IS31FL3746A.

The timing diagram for the I2C is shown in Figure 3. The SDA is latched in on the stable high level of the SCL. When there is no interface activity, the SDA line should be held high.

The "START" signal is generated by lowering the SDA signal while the SCL signal is high. The start signal will alert all devices attached to the I2C bus to check the incoming address against their own chip address.

The 8-bit chip address is sent next, most significant bit first. Each address bit must be stable while the SCL level is high.



After the last bit of the chip address is sent, the master checks for the IS31FL3746A's acknowledge. The master releases the SDA line high (through a pull-up resistor). Then the master sends an SCL pulse. If the IS31FL3746A has received the address correctly, then it holds the SDA line low during the SCL pulse. If the SDA line is not low, then the master should send a "STOP" signal (discussed later) and abort the transfer.

Following acknowledge of IS31FL3746A, the register address byte is sent, most significant bit first. IS31FL3746A must generate another acknowledge indicating that the register address has been received.

Then 8-bit of data byte are sent next, most significant bit first. Each data bit should be valid while the SCL level is stable high. After the data byte is sent, the IS31FL3746A must generate another acknowledge to indicate that the data was received.

The "STOP" signal ends the transfer. To signal "STOP", the SDA signal goes high while the SCL signal is high.

ADDRESS AUTO INCREMENT

To write multiple bytes of data into IS31FL3746A, load the address of the data register that the first data byte is intended for. During the IS31FL3746A acknowledge of receiving the data byte, the internal address pointer will increment by one. The next data byte sent to IS31FL3746A will be placed in the new address, and so on. The auto increment of the address will continue as long as data continues to be written to IS31FL3746A (Figure 6).

READING OPERATION

Most of the registers can be read.

To read the FCh, FEh, after I2C start condition, the bus master must send the IS31FL3746A device

address with the R/\overline{W} bit set to "0", followed by the register address (FEh or F1h) which determines which register is accessed. Then restart I2C, the bus master should send the IS31FL3746A device address with

the R/W bit set to "1". Data from the register defined by the command byte is then sent from the IS31FL3746A to the master (Figure 7).

To read the registers of Page 0 thru Page 1, the FDh should write with 00h before follow the Figure 7 sequence to read the data. That means, when you want to read registers of Page 0, the FDh should point to Page 0 first and you can read the Page 0 data.





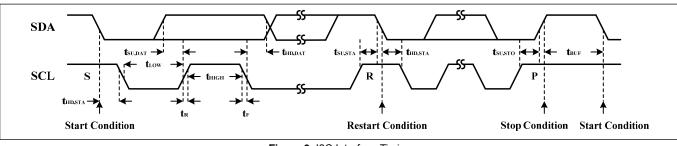
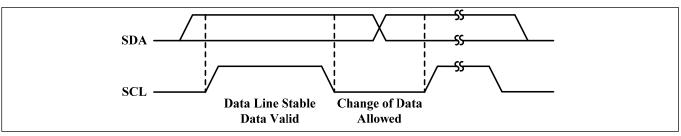
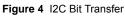


Figure 3 I2C Interface Timing





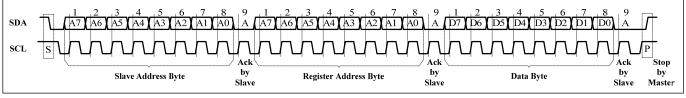


Figure 5 I2C Writing to IS31FL3746A (Typical)

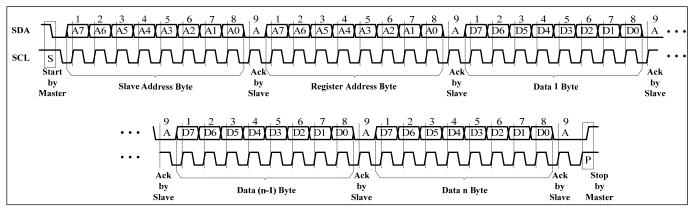


Figure 6 I2C Writing to IS31FL3746A (Automatic Address Increment)

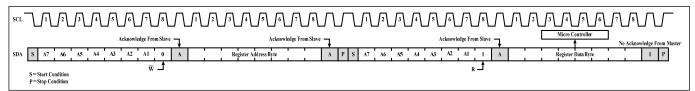


Figure 7 I2C Reading from IS31FL3746A



Table 2 Command Register Definition

Address	Name	Function		R/W	Default
FEh	Command Register Write Lock	To unlock Command Register	4	R/W	0000 0000
FDh	Command Register	Available Page 0 to Page 1 Registers	3	W	XXXX XXXX
FCh	ID Register	For read the product ID only Read result is the slave address	-	R	Slave Address

REGISTER CONTROL

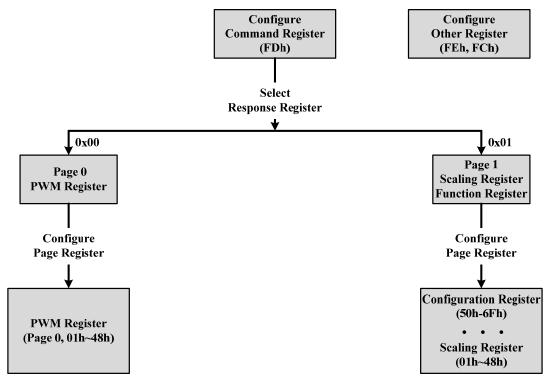


Table 3 FDh Command Register

Data	Function
0000 0000	Point to Page 0 (PG0, PWM Register is available)
0000 0001	Point to Page 1 (PG1, White balance Scaling and Function Register is available)
Others	Reserved

Note: FDh is locked when power up, need to unlock this register before write command to it. See Table 4 for detail.

The Command Register should be configured first after writing in the slave address to choose the available register. Then write data in the choosing register. Power up default state is "0000 0000".

For example, when write "0000 0001" in the Command Register (FDh), the data which writing after will be stored PG1 Register. Write new data can configure other registers.

Table 4 FEh Command Register Write Lock (Read/Write)

Bit	D7:D0	
Name	CRWL	
Default	0000 0000 (FDh write disable)	

To select the PG0~PG1, need to unlock this register first, with the purpose to avoid mis-operation of this register. When FEh is written with 0xC5, FDh is allowed to modify once, after the FDh is modified the FEh will reset to be 0x00 at once.



Table 5 Register Definition

Address	Name	Function		R/W	Default		
PG0 (0x00)	PG0 (0x00): PWM Registers						
01h~48h	PWM Register	Set PWM for each LED	6	R/W	0000 0000		
PG1 (0x01)	: LED Scaling & Function Re	gisters					
01h~48h	Scaling Register	Set Scaling for each LED	7	R/W	0000 0000		
50h	Configuration Register	Configure the operation mode	9	R/W	0000 0000		
51h	Global Current Control Register	Set the global current	10	R/W	0000 0000		
52h	Pull Down/Up Resistor Selection Register	Set the pull down resistor for SWx and pull up resistor for CSy	11	R/W	0011 0011		
53h~5Eh	Open/Short Register	Store the open or short information	12	R	0000 0000		
5Fh	Temperature Status	Store the temperature point of the IC	13	R/W	0000 0000		
60h	Spread Spectrum Register	Spread spectrum function enable	14	R/W	0000 0000		
8Fh	Reset Register	Reset all register to POR state	-	W	0000 0000		
E0h	PWM Frequency Enable Register	Enable PWM frequency setting	15	R/W	0000 0000		
E2h	PWM Frequency Setting Register	Set the PWM frequency	16	R/W	0000 0000		



Page 0 (PG0, FDh= 0x00): PWM Register

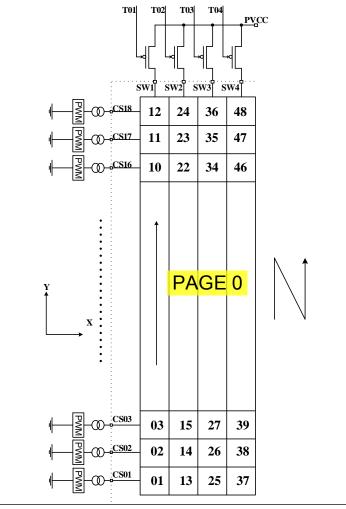


Figure 8 PWM Register

Table 6 PG0: 01h ~ 48h PWM Register

Bit	D7:D0
Name	PWM
Default	0000 0000

Each dot has a byte to modulate the PWM duty in 256 steps.

The value of the PWM Registers decides the average current of each LED noted I_{LED} .

 I_{LED} computed by Formula (1):

$$I_{LED} = \frac{PWM}{256} \times I_{OUT(PEAK)} \times Duty (1)$$
$$PWM = \sum_{n=0}^{7} D[n] \cdot 2^{n}$$

Where Duty is the duty cycle of SWx,

$$Duty = \frac{33\mu s}{(33\mu s + 0.83\mu + 0.3s)} \times \frac{1}{4} = \frac{1}{4.14}$$
(2)

 I_{OUT} is the output current of CSy (y=1~18),

$$I_{OUT(PEAK)} = \frac{343}{R_{ISET}} \times \frac{GCC}{256} \times \frac{SL}{256}$$
(3)

GCC is the Global Current Control Register (PG2, F2h) value, SL is the Scaling Register value as Table 9 and R_{ISET} is the external resistor of ISET pin. D[n] stands for the individual bit value, 1 or 0, in location n.

For example: if D7:D0=1011 0101 (0xB5, 181), GCC=1111 1111, R_{ISET} =10k Ω , SL=1111 1111:

$$I_{LED} = \frac{343}{10\,k\Omega} \times \frac{255}{256} \times \frac{255}{256} \times \frac{1}{4.14} \times \frac{181}{256}$$



Page 1 (PG1, FDh= 0x01): Scaling Register

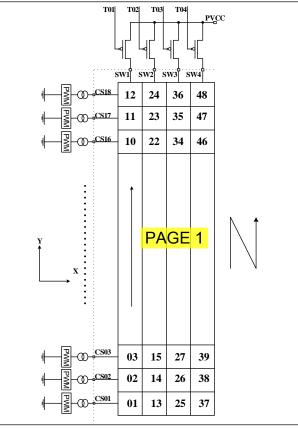


Figure 9 Scaling Register

Table 7 PG1: 01h ~ 48h Scaling Register

Bit	D7:D0	
Name	SL	
Default	0000 0000	

Scaling register control the DC output current of each dot. Each dot has a byte to modulate the scaling in 256 steps.

The value of the Scaling Register decides the peak current of each LED noted $I_{OUT(PEAK)}$.

I_{OUT(PEAK)} computed by Formula (3):

$$I_{OUT(PEAK)} = \frac{343}{R_{ISET}} \times \frac{GCC}{256} \times \frac{SL}{256}$$
(3)
$$SL = \sum_{n=0}^{7} D[n] \cdot 2^{n}$$

 I_{OUT} is the output current of CSy (y=1~18), GCC is the Global Current Control Register (PG1, 51h) value and R_{SET} is the external resistor of R_{SET} pin. D[n] stands for the individual bit value, 1 or 0, in location n.

For example: if R_{SET} =10k Ω , GCC=1111 1111, SL=0111 1111:

$$SL = \sum_{n=0}^{7} D[n] \cdot 2^{n} = 127$$
$$I_{OUT} = \frac{343}{10k\Omega} \times \frac{255}{256} \times \frac{127}{256} = 16.8mA$$
$$I_{LED} = 16.8mA \times \frac{1}{4.14} \times \frac{PWM}{256}$$



Table 8 Page 1 (PG1, FDh= 0x01): Function Register

Register	Name	Function	Table	R/W	Default
50h	Configuration Register	Configure the operation mode	9	R/W	0000 0000
51h	Global Current Control Register	Set the global current	10	R/W	0000 0000
52h	Pull Down/Up Resistor Selection Register	Set the pull down resistor for SWx and pull up resistor for CSy	11	R/W	0011 0011
53h~5Eh	Open/Short Register	Store the open or short information	12	R	0000 0000
5Fh	Temperature Status	Store the temperature point of the IC	13	R/W	0000 0000
60h	Spread Spectrum Register	Spread spectrum function enable	14	R/W	0000 0000
8Fh	Reset Register	Reset all register to POR state	-	W	0000 0000
E0h	PWM Frequency Enable Register	Enable PWM frequency setting	15	R/W	0000 0000
E2h	PWM Frequency Setting Register	Set the PWM frequency	16	R/W	0000 0000

Table 9 50h Configuration Register

Bit	D7:D4	D3	D2:D1	D0
Name	SWS	-	OSDE	SSD
Default	0000	0	00	0

The Configuration Register sets operating mode of IS31FL3746A.

- SSD Software Shutdown Control
- 0 Software shutdown
- 1 Normal operation
- **OSDE** Open Short Detection Enable
- 00 Disable open/short detection
- 01/11 Enable open detection
- 10 Enable short detection
- SWS SWx Setting
- 0000 SW1~SW4, 1/4
- 0001 SW1~SW3, 1/3, SW4 no-active
- 0010 SW1~SW2, 1/2, SW3~SW4 no-active
- All CSx work as current sinks only, no scan
- Others SW1~SW4, 1/4

When OSDE set to "01", open detection will be trigger once, the user could trigger open detection again by set OSDE from "00" to "01".

When OSDE set "10", short detection will be trigger once, the user could trigger short detection again by set OSDE from "00" to "10".

When SSD is "0", IS31FL3746A works in software shutdown mode and to normal operate the SSD bit should set to "1".

SWS control the duty cycle of the SWx, default mode is 1/4.

Table 10 51h Global Current Control Register

Bit	D7:D0
Name	GCC
Default	0000 0000

The Global Current Control Register modulates all CSy (y=1~18) DC current which is noted as I_{OUT} in 256 steps.

I_{OUT} is computed by the Formula (3):

$$I_{OUT(PEAK)} = \frac{343}{R_{EXT}} \times \frac{GCC}{256} \times \frac{SL}{256}$$
(3)
$$GCC = \sum_{n=0}^{7} D[n] \cdot 2^{n}$$

Where D[n] stands for the individual bit value, 1 or 0, in location n.

Table 1152hPull Down/UpResistor SelectionRegister

Bit	D7	D6:D4	D3	D2:D0
Name	PHC	SWPDR	-	CSPUR
Default	0	011	0	011

Set pull down resistor for SWx and pull up resistor for CSy.

PHC Phase choice

- 0 0 degree phase delay
- 1 180 degree phase delay



SWPD	R SWx Pull down Resistor Selection Bit
000	No pull down resistor
001	0.5kΩ only in SWx off time
010	1.0kΩ only in SWx off time
011	2.0k Ω only in SWx off time
100	1.0k Ω all the time
101	2.0k Ω all the time
110	4.0k Ω all the time
111	8.0k Ω all the time
CSPU	R CSy Pull up Resistor Selection Bit
CSPUI 000	R CSy Pull up Resistor Selection Bit No pull up resistor
000	No pull up resistor
000 001	No pull up resistor $0.5k\Omega$ only in CSx off time
000 001 010	No pull up resistor 0.5k Ω only in CSx off time 1.0k Ω only in CSx off time
000 001 010 011	No pull up resistor 0.5k Ω only in CSx off time 1.0k Ω only in CSx off time 2.0k Ω only in CSx off time
000 001 010 011 100	No pull up resistor $0.5k\Omega$ only in CSx off time $1.0k\Omega$ only in CSx off time $2.0k\Omega$ only in CSx off time $1.0k\Omega$ all the time

111 8.0k Ω all the time

Table 12 53h~5Eh Open/Short Register (Read Only)

Bit	D7:D6	D5:D0
Name	-	CS18:CS13, CS12:CS07,CS06:CS01
Default	00	00 0000

When OSDE (PG1, 00h) is set to "01", open detection will be trigger once, and the open information will be stored at 53h~5Eh.

When OSDE (PG1, 00h) set to "10", short detection will be trigger once, and the short information will be stored at 53h~5Eh.

Before set OSDE, the GCC should set to 0x01.

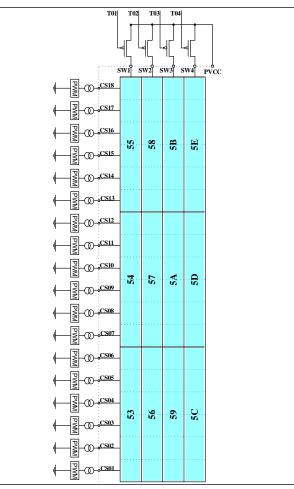


Figure 10 Open/Short Register

Table 13 5Fh Temperature Status

Bit	D7:D4	D3:D2	D1:D0
Name	-	TS	TROF
Default	0000	00	00

TS store the temperature point of the IC. If the IC temperature reaches the temperature point the IC will trigger the thermal roll off and will decrease the current as TROF set percentage.

TROF percentage of output current

- 00 100%
- 01 75%
- 10 55%
- 11 30%

TS Temperature Point, Thermal roll off start point

- 00 140°C
- 01 120°C
- 10 100°C
- 11 90°C



Table 14 60h Spread Spectrum Register

Bit	D7:D6	D4	D3:D2	D1:D0
Name	-	SSP	RNG	CLT
Default	00	0	00	00

When SSP enable, the spread spectrum function will be enabled and the RNG & CLT bits will adjust the range and cycle time of spread spectrum function.

SSP Spread spectrum function	enable
------------------------------	--------

- 0 Disable
- 1 Enable

RNG Spread spectrum range

- 00 ±5%
- 01 ±15%
- 10 ±24%
- 11 ±34%

CLT Spread spectrum cycle time

- 00 1980µs
- 01 1200µs
- 10 820µs
- 11 660µs

8Fh Reset Register

Once user writes the Reset Register with 0xAE, IS31FL3746A will reset all the IS31FL3746A registers to their default value. On initial power-up, the IS31FL3746A registers are reset to their default values for a blank display.

Table 15 E0h PWM Frequency Enable Register

Bit	D7:D1	D0
Name	-	PFEN
Default	0000 000	0

The PWM Frequency Enable Register enables or disables to change the PWM frequency. If PFEN='1', user can change the PWM frequency by modifying the E2h register.

PFEN PWM Frequency Enable

- 0 Disable
- 1 Enable

Table 16 E2h PWM Frequency Setting Register

Bit	D7:D5	D4:D0
Name	PF	-
Default	000	0 0000

PWM Frequency Setting Register is used to set the PWM frequency.

PF	PWM Frequency	
000/111	29kHz	
001	14.5kHz	
010	7.25kHz	
011	3.63kHz	
100	1.81kHz	
101	906Hz	
110	453Hz	



CLASSIFICATION REFLOW PROFILES

Profile Feature	Pb-Free Assembly
Preheat & Soak Temperature min (Tsmin) Temperature max (Tsmax) Time (Tsmin to Tsmax) (ts)	150°C 200°C 60-120 seconds
Average ramp-up rate (Tsmax to Tp)	3°C/second max.
Liquidous temperature (TL) Time at liquidous (tL)	217°C 60-150 seconds
Peak package body temperature (Tp)*	Max 260°C
Time (tp)** within 5°C of the specified classification temperature (Tc)	Max 30 seconds
Average ramp-down rate (Tp to Tsmax)	6°C/second max.
Time 25°C to peak temperature	8 minutes max.

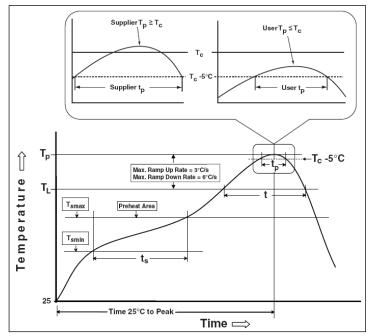
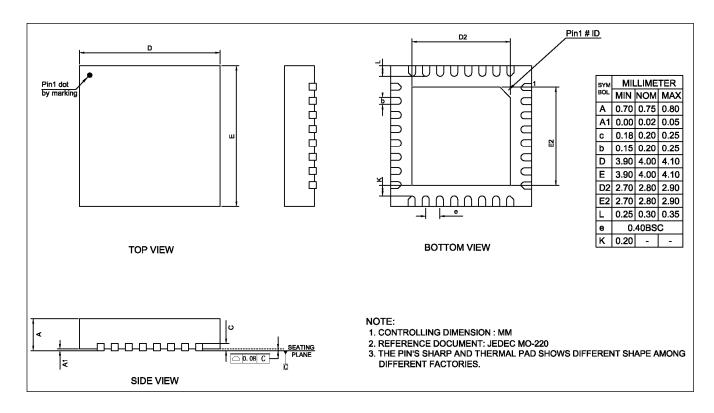


Figure 11 Classification Profile



PACKAGE INFORMATION

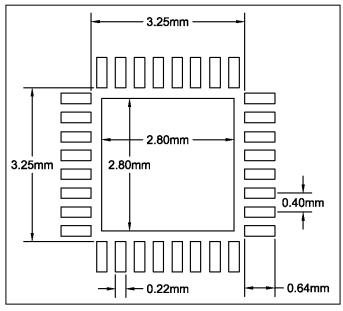
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RECOMMENDED LAND PATTERN

QFN-32



Note:

1. Land pattern complies to IPC-7351.

2. All dimensions in MM.

3. This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depends on many factors unknown (eg. User's board manufacturing specs), user must determine suitability for use.



REVISION HISTORY

Revision	Detail Information	Date
0A	Initial release	2018.08.16